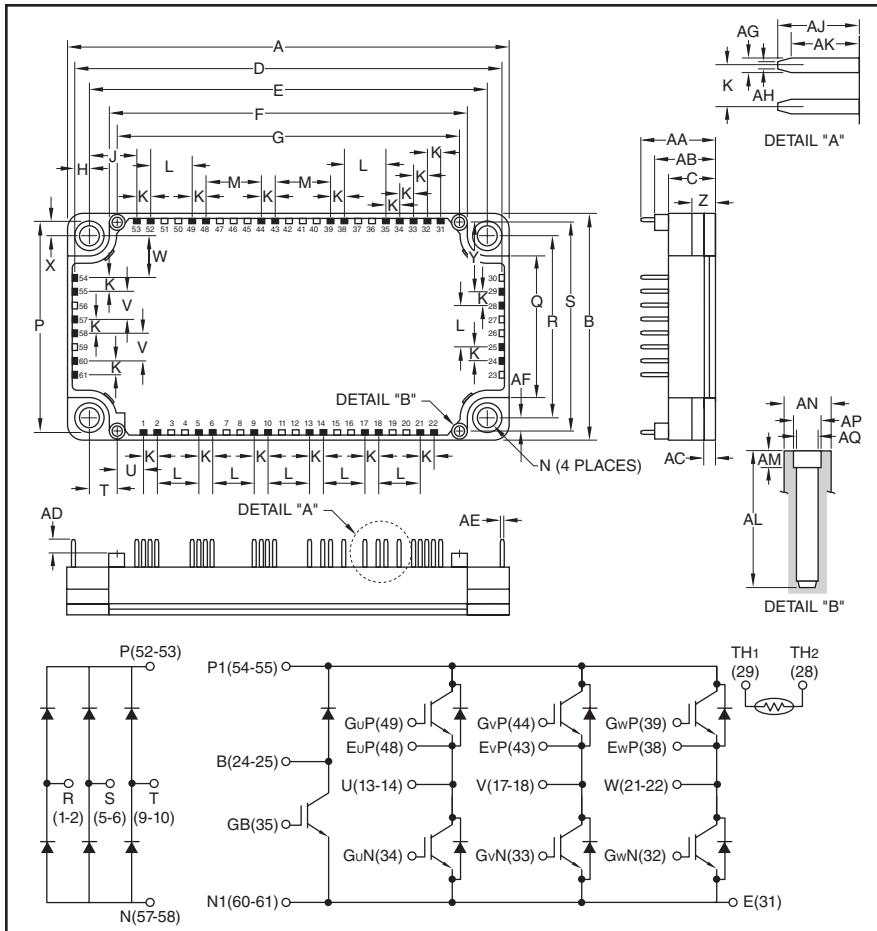


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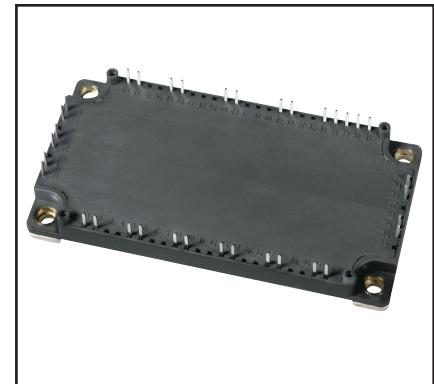
**NX-Series CIB Module**

(3Ø Converter + 3Ø Inverter + Brake)

100 Amperes/600 Volts


**Outline Drawing and Circuit Diagram**

Dimensions	Inches	Millimeters
A	4.79	121.7
B	2.44	62.0
C	0.51	13.0
D	4.65	118.1
E	4.33±0.02	110.0±0.5
F	3.89	99.0
G	3.72	94.5
H	0.16	4.06
J	0.51	13.09
K	0.15	3.81
L	0.45	11.43
M	0.6	15.24
N	0.22 Dia.	5.5 Dia.
P	2.30	58.4
Q	1.53	39.0
R	1.97±0.02	50.0±0.5
S	2.26	57.5
T	0.30	7.75
U	0.28	7.25
V	0.3	7.62


**Description:**

CIBs are low profile and thermally efficient. Each module consists of a three-phase diode converter section, a three-phase inverter section and a brake circuit. A thermistor is included in the package for sensing the baseplate temperature. 5th Generation CSTBT chips yield low loss.

**Features:**

- Low Drive Power
- Low  $V_{CE(sat)}$
- Discrete Super-Fast Recovery Free-Wheel Diode
- Isolated Baseplate for Easy Heat Sinking

**Applications:**

- AC Motor Control
- Motion/Servo Control
- Photovoltaic/Fuel Cell

**Ordering Information:**

Example: Select the complete module number you desire from the table below -i.e.

CM100MX-12A is a 600V ( $V_{CES}$ ), 100 Ampere CIB Power Module.

Type	Current Rating Amperes	$V_{CES}$ Volts (x 50)
CM	100	12



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#### **CM100MX-12A**

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**Absolute Maximum Ratings,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	CM100MX-12A	Units
Power Device Junction Temperature	$T_j$	-40 to 150	°C
Storage Temperature	$T_{stg}$	-40 to 125	°C
Mounting Torque, M5 Mounting Screws	—	31	in-lb
Module Weight (Typical)	—	270	Grams
Isolation Voltage, AC 1 minute, 60Hz Sinusoidal	$V_{ISO}$	2500	Volts

#### **Inverter Sector**

Collector-Emitter Voltage (G-E Short)	$V_{CES}$	600	Volts
Gate-Emitter Voltage (C-E Short)	$V_{GES}$	$\pm 20$	Volts
Collector Current ( $T_C = 75^\circ\text{C}$ )*	$I_C$	100	Amperes
Peak Collector Current**	$I_{CM}$	200	Amperes
Emitter Current ( $T_C = 25^\circ\text{C}$ , $T_j < 150^\circ\text{C}$ )*	$I_E^{***}$	100	Amperes
Peak Emitter Current ( $T_j < 150^\circ\text{C}$ )**	$I_{EM}^{***}$	200	Amperes
Maximum Collector Dissipation ( $T_C = 25^\circ\text{C}$ , $T_j < 150^\circ\text{C}$ )*	$P_C$	400	Watts

#### **Brake Sector**

Collector-Emitter Voltage (G-E Short)	$V_{CES}$	600	Volts
Gate-Emitter Voltage (C-E Short)	$V_{GES}$	$\pm 20$	Volts
Collector Current ( $T_C = 97^\circ\text{C}$ )*	$I_C$	50	Amperes
Peak Collector Current**	$I_{CM}$	100	Amperes
Maximum Collector Dissipation ( $T_C = 25^\circ\text{C}$ , $T_j < 150^\circ\text{C}$ )*	$P_C$	280	Watts
Repetitive Peak Reverse Voltage (Clamp Diode Part)	$V_{RRM}^{***}$	600	Volts
Forward Current ( $T_C = 25^\circ\text{C}$ )*	$I_F^{***}$	50	Amperes
Forward Current (Clamp Diode Part)**	$I_{FM}^{***}$	100	Amperes

#### **Converter Sector**

Repetitive Peak Reverse Voltage	$V_{RRM}$	800	Volts
Recommended Input Voltage	$E_a$	220	Volts RMS
DC Output Current (3-Phase Full Wave Rectifying, $T_C = 137^\circ\text{C}$ )*	$I_O$	100	Amperes
Surge Forward Current (sine Half-wave 1 Cycle Peak Value, $F = 60\text{Hz}$ , Non-repetitive)	$I_{FSM}$	1000	Amperes
Current Square Time (Value for One Cycle of Surge Current)	$I^2t$	4160	$\text{A}^2\text{s}$

\* $T_C$ ,  $T_f$  measured point is just under the chips.

\*\*Pulse width and repetition rate should be such that device junction temperature ( $T_j$ ) does not exceed  $T_{j(\max)}$  rating.

\*\*\*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

**CM100MX-12A**
**NX-Series CIB Module**
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100 Amperes/600 Volts

**Electrical and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**
**Inverter Sector**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units	
Collector Cutoff Current	$I_{CES}$	$V_{CE} = V_{CES}$ , $V_{GE} = 0\text{V}$	—	—	1.0	mA	
Gate-Emitter Threshold Voltage	$V_{GE(\text{th})}$	$I_C = 10\text{mA}$ , $V_{CE} = 10\text{V}$	5	6	7	Volts	
Gate Leakage Current	$I_{GES}$	$V_{GE} = V_{GES}$ , $V_{CE} = 0\text{V}$	—	—	0.5	$\mu\text{A}$	
Collector-Emitter Saturation Voltage	$V_{CE(\text{sat})}$	$I_C = 100\text{A}$ , $V_{GE} = 15\text{V}$ , $T_j = 25^\circ\text{C}$	—	1.7	2.1	Volts	
		$I_C = 100\text{A}$ , $V_{GE} = 15\text{V}$ , $T_j = 125^\circ\text{C}$	—	1.9	—	Volts	
		$I_C = 100\text{A}$ , $V_{GE} = 15\text{V}$ , Chip	—	1.6	—	Volts	
Input Capacitance	$C_{ies}$		—	—	11.3	nF	
Output Capacitance	$C_{oes}$	$V_{CE} = 10\text{V}$ , $V_{GE} = 0\text{V}$	—	—	1.4	nF	
Reverse Transfer Capacitance	$C_{res}$		—	—	0.45	nF	
Total Gate Charge	$Q_G$	$V_{CC} = 300\text{V}$ , $I_C = 100\text{A}$ , $V_{GE} = 15\text{V}$	—	270	—	nC	
Inductive Load	Turn-on Delay Time	$t_{d(\text{on})}$	—	—	100	ns	
Load	Turn-on Rise Time	$t_r$	$V_{CC} = 300\text{V}$ , $I_C = 100\text{A}$ ,	—	—	100	ns
Switch	Turn-off Delay Time	$t_{d(\text{off})}$	$V_{GE} = \pm 15\text{V}$ ,	—	—	300	ns
Time	Turn-off Fall Time	$t_f$	$R_G = 6.2\Omega$ , $I_E = 100\text{A}$ ,	—	—	600	ns
Reverse Recovery Time*	$t_{rr}$	Inductive Load Switching Operation	—	—	200	ns	
Reverse Recovery Charge*	$Q_{rr}$		—	3.6	—	$\mu\text{C}$	
Emitter-Collector Voltage*	$V_{EC}$	$I_E = 100\text{A}$ , $V_{GE} = 0\text{V}$	—	2.0	2.8	Volts	
		$I_E = 100\text{A}$ , $V_{GE} = 0\text{V}$ , Chip	—	1.9	—	Volts	

**Thermal and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

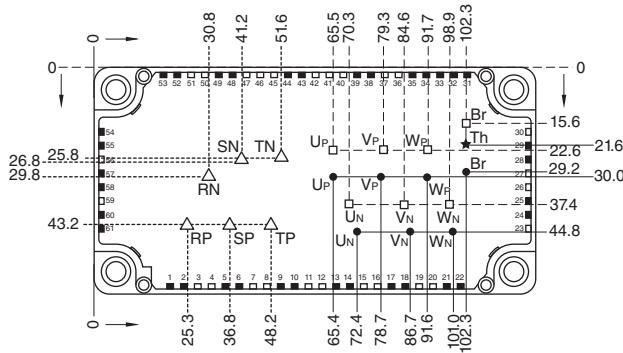
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case**	$R_{th(j-c)Q}$	Per IGBT	—	—	0.31	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case**	$R_{th(j-c)D}$	Per FWDi	—	—	0.59	$^\circ\text{C}/\text{W}$
Contact Thermal Resistance**	$R_{th(c-f)}$	Thermal Grease Applied	—	0.015	—	$^\circ\text{C}/\text{W}$
Internal Gate Resistance	$R_{Gint}$	$T_C = 25^\circ\text{C}$	—	0	—	$\Omega$
External Gate Resistance	$R_G$		6.0	—	63	$\Omega$

\*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

\*\* $T_C$ ,  $T_f$  measured point is just under the chips.

**CHIP LOCATION (TOP VIEW)**

□ IGBT    ● FWDi    △ Converter Diode    ★ NTC Thermistor


Dimensions in mm (Tolerance:  $\pm 1\text{mm}$ )



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#### CM100MX-12A

#### NX-Series CIB Module

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#### Electrical and Mechanical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

##### Brake Sector

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector Cutoff Current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0V$	—	—	1.0	mA
Gate-Emitter Threshold Voltage	$V_{GE(\text{th})}$	$I_C = 5\text{mA}$	5	6	7	Volts
Gate Leakage Current	$I_{GES}$	$V_{GE} = V_{GES}, V_{CE} = 0V$	—	—	0.5	$\mu\text{A}$
Collector-Emitter Saturation Voltage	$V_{CE(\text{sat})}$	$I_C = 50\text{A}, V_{GE} = 15\text{V}, T_j = 25^\circ\text{C}$	—	1.7	2.1	Volts
		$I_C = 50\text{A}, V_{GE} = 15\text{V}, T_j = 125^\circ\text{C}$	—	1.9	—	Volts
		$I_C = 50\text{A}, V_{GE} = 15\text{V}, \text{Chip}$	—	1.6	—	Volts
Input Capacitance	$C_{ies}$		—	—	7.5	nF
Output Capacitance	$C_{oes}$	$V_{CE} = 10\text{V}, V_{GE} = 0V$	—	—	1.0	nF
Reverse Transfer Capacitance	$C_{res}$		—	—	0.3	nF
Total Gate Charge	$Q_G$	$V_{CC} = 300\text{V}, I_C = 50\text{A}, V_{GE} = 15\text{V}$	—	200	—	nC
Repetitive Reverse Current*	$I_{RRM}$	$V_R = V_{RRM}$	—	—	1.0	mA
Forward Voltage Drop *	$V_F$	$I_F = 50\text{A}$	—	2.3	3.2	Volts
		$I_F = 50\text{A}, \text{Chip}$	—	2.2	—	Volts

#### Thermal and Mechanical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case**	$R_{th(j-c)Q}$	Per IGBT	—	—	0.44	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case**	$R_{th(j-c)D}$	Per FWDi	—	—	0.85	$^\circ\text{C}/\text{W}$
Contact Thermal Resistance**	$R_{th(c-f)}$	Thermal Grease Applied	—	0.015	—	$^\circ\text{C}/\text{W}$
Internal Gate Resistance	$R_{Gint}$	$T_C = 25^\circ\text{C}$	—	0	—	$\Omega$
External Gate Resistance	$R_G$		13	—	125	$\Omega$

#### Converter Sector, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Repetitive Peak Reverse Current	$I_{RRM}$	$V_R = V_{RRM}, T_j = 150^\circ\text{C}$	—	—	20	mA
Forward Voltage Drop	$V_F$	$I_F = 100\text{A}$	—	1.2	1.6	Volts
Thermal Resistance, Junction to Case**	$R_{th(j-c)}$	Per FWDi	—	—	0.24	K/W
Contact Thermal Resistance**	$R_{th(c-f)}$	Thermal Grease Applied	—	0.015	—	$^\circ\text{C}/\text{W}$

#### NTC Thermistor Sector, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Zero Power Resistance	$R$	$T_C = 25^\circ\text{C}$	4.85	5.00	5.15	$\text{k}\Omega$
Deviation of Resistance	$\Delta R/R$	$T_C = 100^\circ\text{C}, R_{100} = 493\Omega$	-7.3	—	+7.8	%
B Constant	$B_{(25/50)}$	$B = (\ln R_1 - \ln R_2) / (1/T_1 - 1/T_2)^{***}$	—	3375	—	K
Power Dissipation	$P_{25}$	$T_C = 25^\circ\text{C}$	—	—	10	mW

\*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

\*\* $T_C, T_f$  measured point is just under the chips.

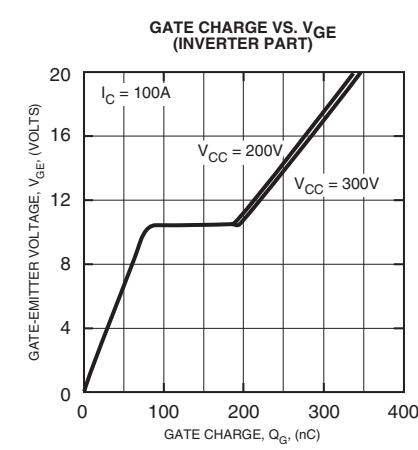
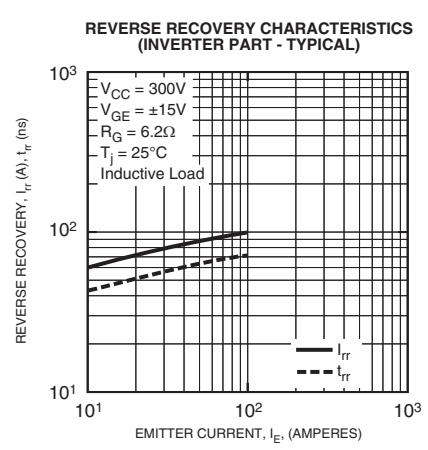
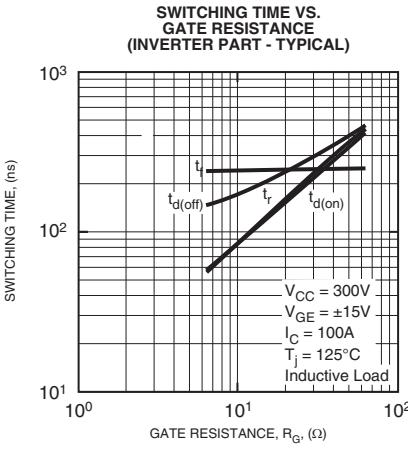
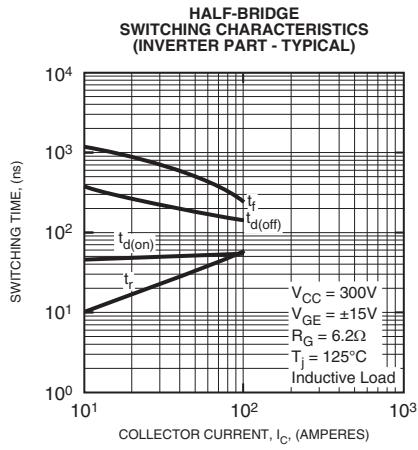
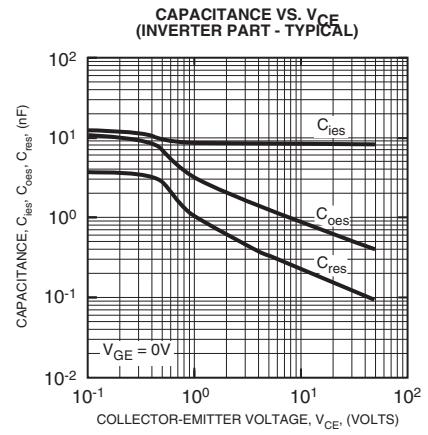
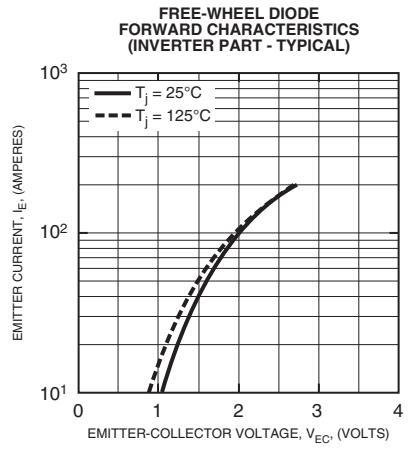
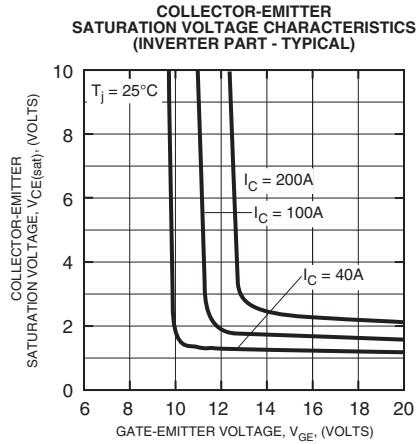
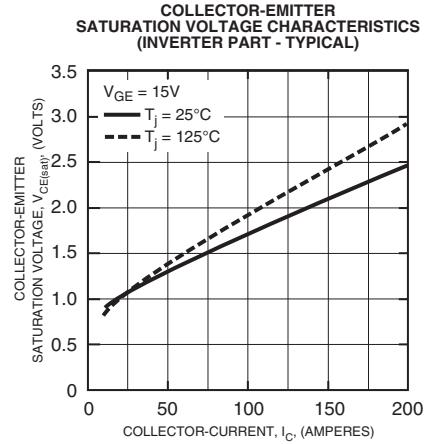
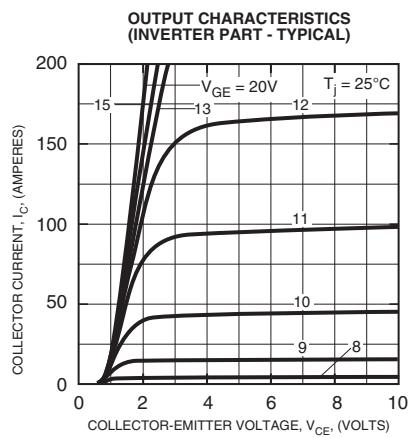
\*\*\* $R_1$ : Resistance at Absolute Temperature  $T_1(\text{K})$ ,  $R_2$ : Resistance at Absolute Temperature  $T_2(\text{K})$ ,  $T(\text{K}) = t(\text{ }^\circ\text{C}) + 273.15$

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100 Amperes/600 Volts



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